

■ Features

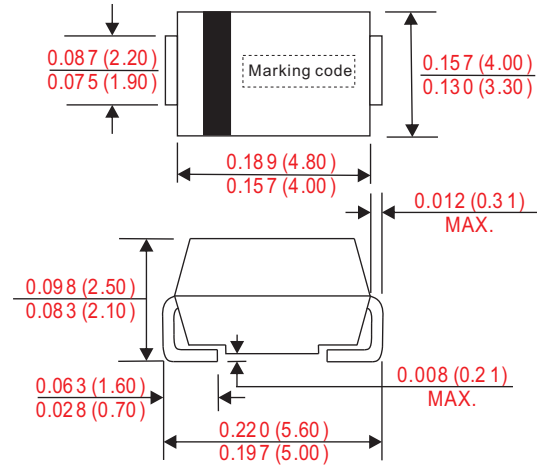
- Low profile surface mounted application in order to optimize board space.
- High current capability.
- High surge capability.
- Glass passivated chip junction inside.
- Suffix "G" indicates Halogen-free part, ex. GS1ABG.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228

■ Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AA / SMB
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Weight : 0.003 ounce, 0.091 gram

■ Outline

SMB(DO-214AA)



■ Maximum ratings and electrical characteristics

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Conditions	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current		I_o			1.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I_{FSM}			30	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^\circ\text{C}$	I_R			1.0	uA
	$V_R = V_{RRM} \quad T_A = 125^\circ\text{C}$				300	
Thermal resistance	Junction to ambient	$R_{\theta JA}$		60		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		15		pF
Storage temperature		T_{STG}	-50		+150	°C

Symbol	Marking code	Max. repetitive peak reverse voltage V_{RRM} (V)	Max. RMS voltage V_{RMS} (V)	Max. DC blocking voltage V_R (V)	Max. forward voltage @1A, $T_A = 25^\circ\text{C}$ V_F (V)	Max. reverse recovery time(1) T_{rr} (us)	Operating temperature T_J (°C)
GS1AB	GS1A	50	35	50	1.10	2.5	-50 ~ +150
GS1BB	GS1B	100	70	100			
GS1DB	GS1D	200	140	200			
GS1GB	GS1G	400	280	400			
GS1JB	GS1J	600	420	600			
GS1KB	GS1K	800	560	800			
GS1MB	GS1M	1000	700	1000			

Note : 1. $I_F = 0.5A$, $I_R = 1.0A$, $I_{RR} = 0.25A$

■ Rating and characteristic curves

FIG.1-TYPICAL FORWARD CHARACTERISTICS

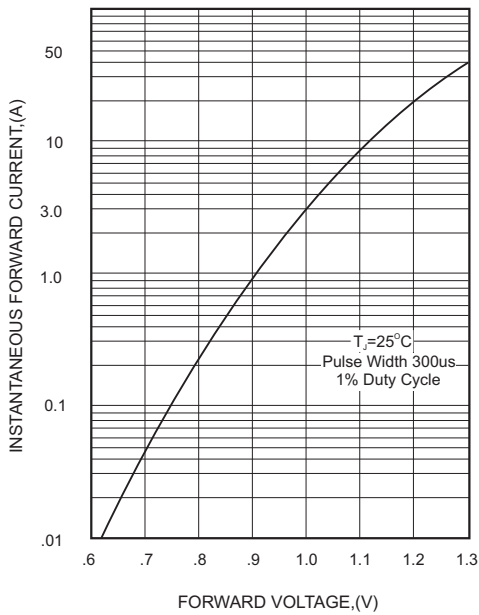


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

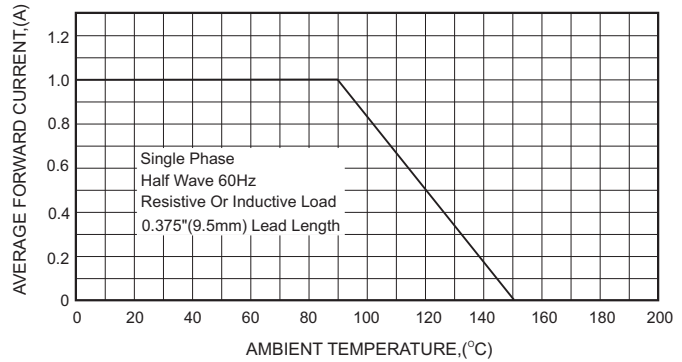


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

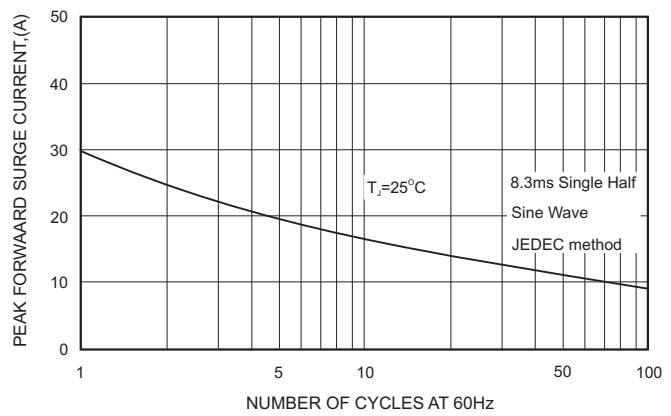


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

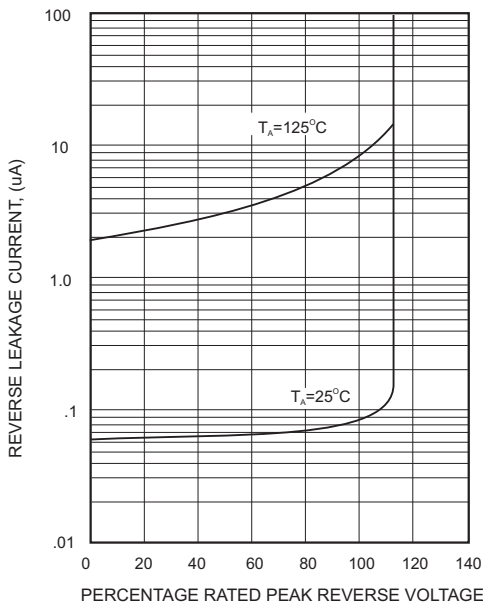
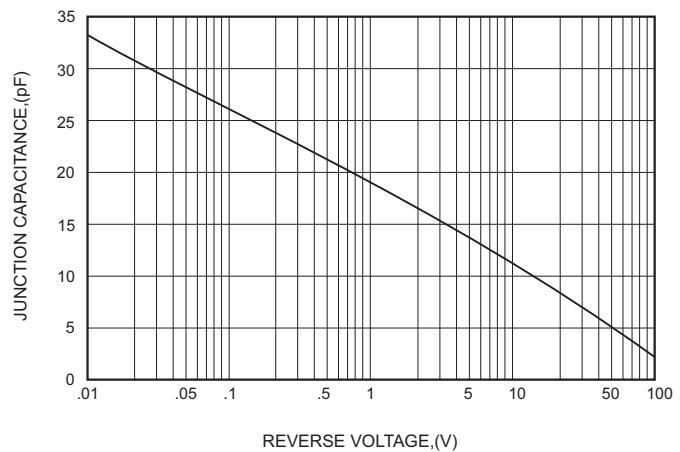
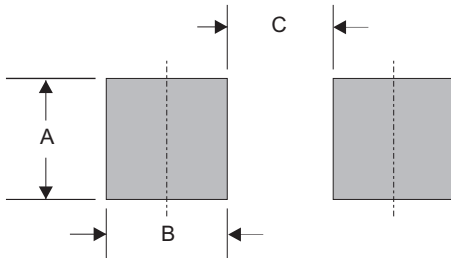


FIG.5-TYPICAL JUNCTION CAPACITANCE



■ SMB foot print



A	B	C
0.091 (2.30)	0.098 (2.50)	0.071 (1.80)

Dimensions in inches and (millimeters)

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